Recently, with the continuous development of industrial electronics technologies, small-size and high-power-density designs became a development trend. Thus, high and very high frequency power supplies received widespread attention. One major advantage of improving the working frequency is to achieve total volume reduction of passive components, and therefore effectively reduce system size and improve power density. Moreover, in some cases, even parasitic parameters of a system working at high and very high frequency can also be used as the passive element. Besides, electrolytic capacitors can be removed thereby greatly extending the system lifetime. The dynamic response can also be accelerated. At the same time, the third generation of wide bandgap semiconductors such as SiC and GaN with material properties superior to their Si counterparts, creates new opportunity and challenges for innovation of power converters such as compact design, thermal management, electromagnetic interference etc. With the maturity of these devices, it provides a broad space for development of high and very high frequency power supplies. Nevertheless, topologies, driving methods, control strategies and many aspects require deep investigation with the increment of switching frequencies. We encourage all researchers working in this area to submit papers to this Special Section.

Editors invite original manuscripts presenting recent advances in these fields with special reference to the following topics:

- Topologies of high and very high frequency power supplies
- Control strategies of high and very high frequency power supplies
- Design of magnetic components in high and very high frequency power supplies
- Effects of parasitic components in high and very high frequency power supplies
- Driving methods of high and very high frequency power supplies
- Applications of wide bandgap devices in high and very high frequency power supplies
- Optimal layout of high and very high frequency power supplies
- EMI characteristics of high and very high frequency power supplies
- High and Very High Frequency Power Supplies for IOT Application

Manuscript Preparation and Submission

Check carefully the style of the journal described in the guidelines “Information for Authors” in the IEEE-IES website: [http://www.ieee-ies.org/pubs/transactions-on-industrial-electronics](http://www.ieee-ies.org/pubs/transactions-on-industrial-electronics).

Please submit your manuscript in electronic form through: [https://mc.manuscriptcentral.com/tie-ieee/](https://mc.manuscriptcentral.com/tie-ieee/).

On the submitting page, in pop-up menu of manuscript type, select: “SS on High & Very High Frequency Power Supplies for Industrial Applications”, then upload all your manuscript files following the instructions given on the screen.

**Corresponding Guest Editor**
Dr./Prof. Yijie Wang
School of Electrical Engineering and Automation
Harbin Institute of Technology
Harbin, China
EMAIL: wangyijie@hit.edu.cn

**Guest Editor**
Dr./Prof. Oscar Lucia
Dept. of Electronic Engineering and Communications
University of Zaragoza
Zaragoza, Spain
EMAIL: olucia@unizar.es

**Guest Editor**
Dr./Prof. Zhe Zhang
Dept. of Electrical Engineering
Technical University of Denmark
Copenhagen, Denmark
EMAIL: zz@elektro.dtu.dk

SS Guest Editors email: SShfpows@ieee-ies.org

**Timetable**

<table>
<thead>
<tr>
<th>Deadline for manuscript submissions:</th>
<th>Information about manuscript acceptance:</th>
<th>Publication Date:</th>
</tr>
</thead>
<tbody>
<tr>
<td>August 31, October 30, 2018</td>
<td>Spring, 2019</td>
<td>Summer, 2019</td>
</tr>
</tbody>
</table>